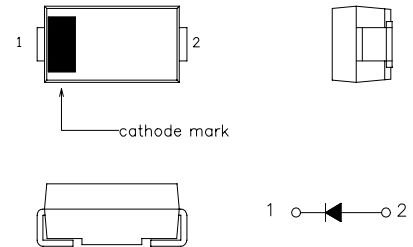


DIODE Type : EC10DS4

FEATURES

- * Miniature Size, Surface Mount Device
- * High Surge Capability
- * Low Forward Voltage Drop
- * Low Reverse Leakage Current
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC10DS4			Unit
Repetitive Peak Reverse Voltage	V _{RRM}	400			V
Non-repetitive Peak Reverse Voltage	V _{RSM}	600			V
Average Rectified Output Current	I _O	0.74	Ta=25 °C *1	50Hz Half Sine Wave Resistive Load	A
		1.0	Ta=25 °C *2		
RMS Forward Current	I _{F(RMS)}	1.57			A
Surge Forward Current	I _{FSM}	25	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T _{jw}	-40 to +150			°C
Storage Temperature Range	T _{stg}	-40 to +150			°C

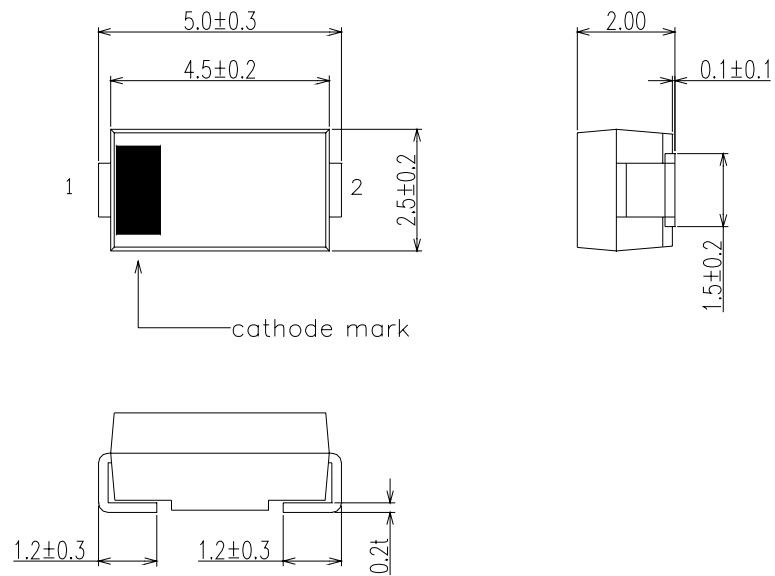
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	I_{RM}	$T_j= 25^{\circ}\text{C}$, $V_{RM}= V_{RRM}$	-	-	10	μA
Peak Forward Voltage	V_{FM}	$T_j= 25^{\circ}\text{C}$, $I_{FM}= 1.0\text{A}$	-	-	1.1	V
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	-	$^{\circ}\text{C} / \text{W}$
			*2	-	-	

*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

EC10DS4 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

